

1N4448WS-FL

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1N4448WS-FL

200mW Surface Mount Switching Diode-100V

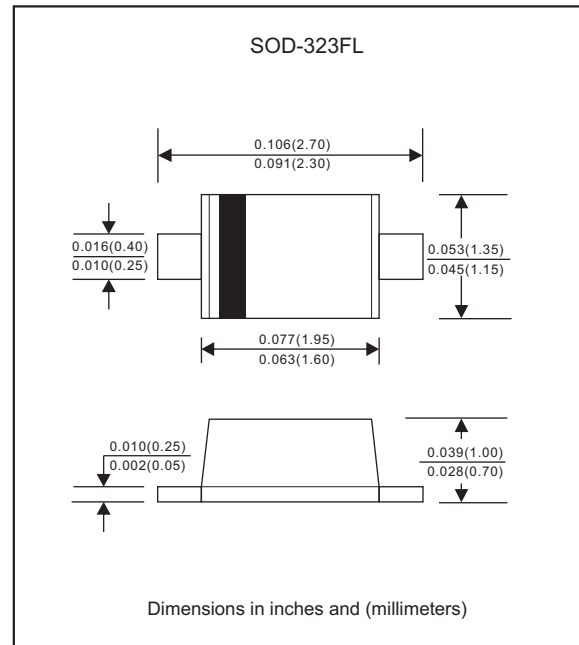
Features

- Fast Switching Device ($t_{rr} < 4.0\text{ns}$).
- General Purpose Diodes.
- Flat Lead SOD-323FL Small Outline Plastic Package.
- Surface Device Type Mounting.
- Lead-free parts for green partner, exceeds environmental standards of MIL-STD-19500 /228
- Suffix "-H" indicates Halogen-free parts, ex. 1N4448WS-FL-H

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-323FL
- Terminals :Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.004 gram

Package Outline



Maximum ratings and Electrical Characteristics (AT $T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	Symbol	1N4448WS-FL	UNIT
Repetitive Peak Reverse Voltage	V_{RRM}	75	V
Non-Repetitive Peak Reverse Voltage	V_{RSM}	100	V
Maximum average forward current at $T_A = 25^\circ\text{C}$	I_O	150	mA
Peak forward surge current, 1.0us	I_{FSM}	2.0	A
Power Dissipation derate above 25°C	P_D	200	mW
Maximum forward voltage	V_F	0.72@0.005A 1.0@0.1A	V
Maximum DC reverse current at rated DC blocking voltage $T_J = 25^\circ\text{C}$	I_R	0.025@20V 5.0@75V	uA
Junction capacitance (Notes 1)	C_J	4.0	pF
Maximum reverse recovery (Notes 2)	t_{rr}	4.0	ns
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

Notes :

1. C_J at $V_R = 0\text{V}$, $f = 1\text{MHz}$

2. From $I_F = 10\text{mA}$ to $I_R = 10\text{mA}$, $I_{RR} = 1\text{mA}$, $R_L = 100\Omega$

Rating and characteristic curves (1N4448WS-FL)

FIG.1-Power Dissipation

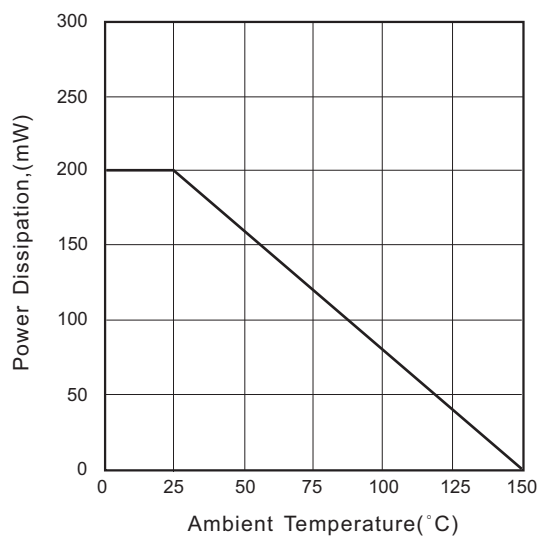


FIG.2 - Typical Reverse Characteristics

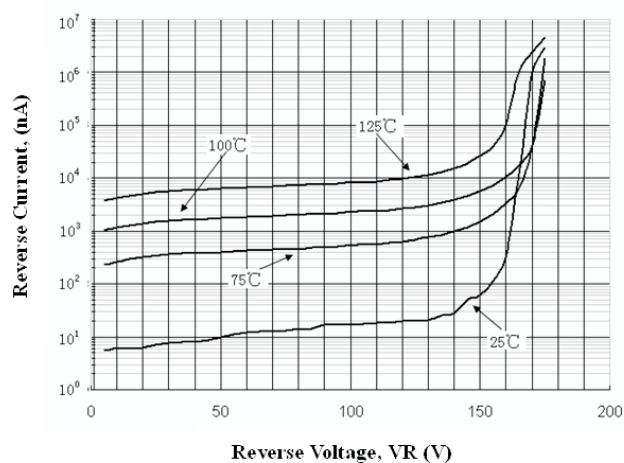


FIG.3 - Typical Capacitance

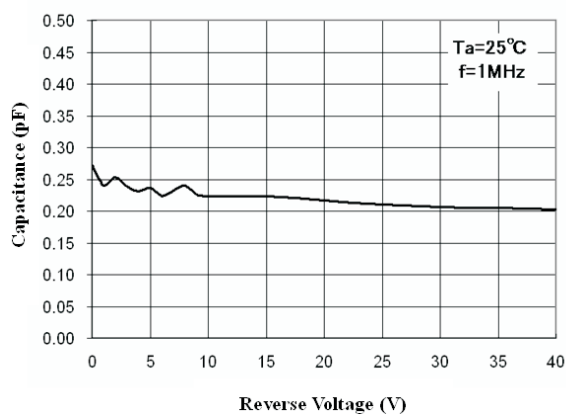
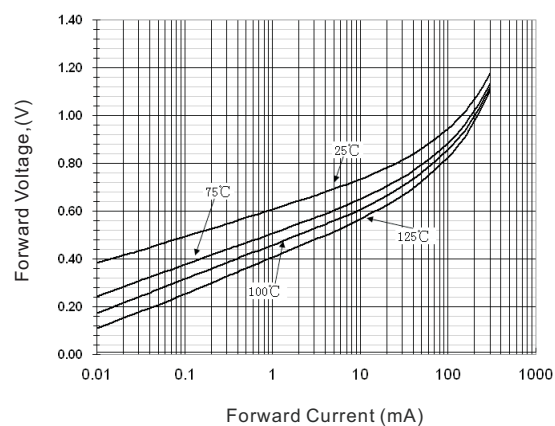


FIG.4 - Typical Forward Voltage vs. Ambient Temperature



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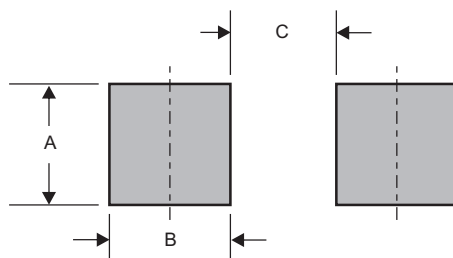
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
1N4448WS-FL	S2

Suggested solder pad layout

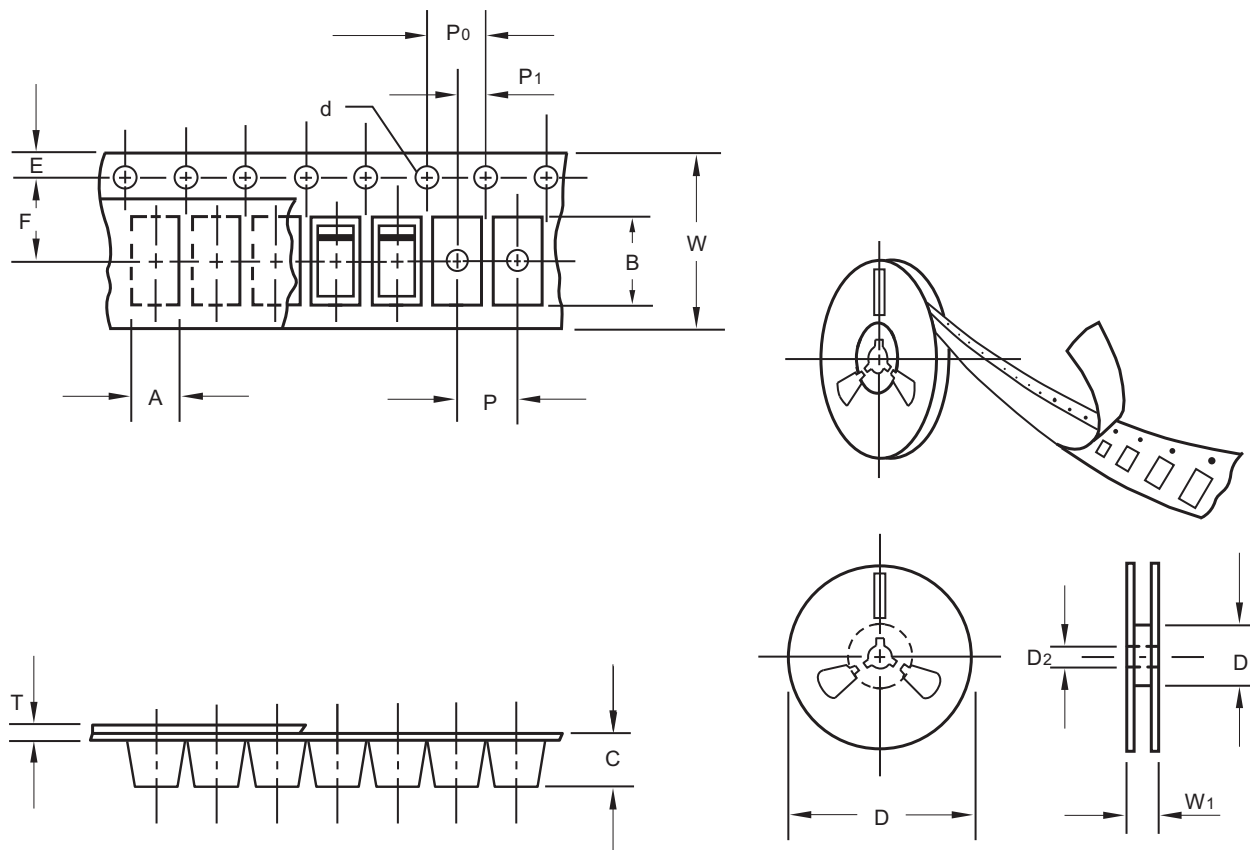


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-323FL	0.032 (0.82)	0.022 (0.56)	0.069 (1.75)

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Packing information



unit:mm

Item	Symbol	Tolerance	SOD-323FL
Carrier width	A	0.1	1.46
Carrier length	B	0.1	2.95
Carrier depth	C	0.1	1.25
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

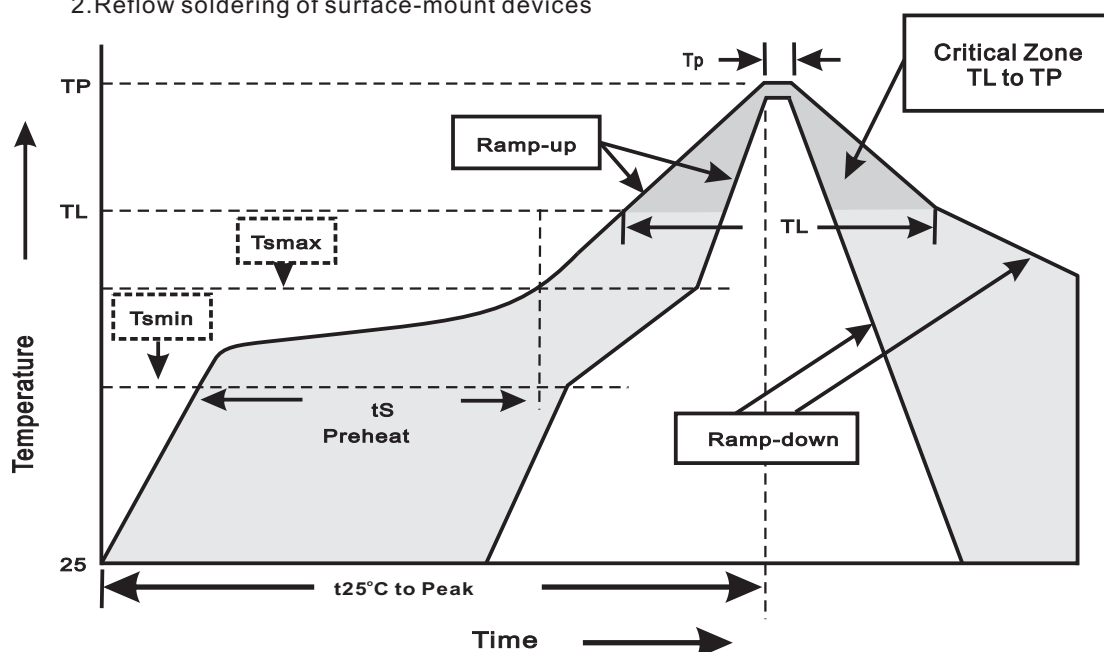
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-323FL	7"	3,000	4.0	30,000	183*183*123	178	382*262*387	240,000	9.5

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smín}) -Temperature Max(T _{smáx}) -Time(min to max)(t _S)	150°C 200°C 60~120sec
T _{smáx} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260\pm 5^{\circ}\text{C}$ for $10\pm 2\text{sec.}$ immerse body into solder $1/16''\pm 1/32''$	MIL-STD-750D METHOD-2031
2. Solderability	at $245\pm 5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^{\circ}\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^{\circ}\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A=121^{\circ}\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Thermal Shock	0°C for 5 min. rise to 100°C for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1056
9. Forward Surge	Peak Forward Surge Current at $t=1\mu\text{s}$	MIL-STD-750D METHOD-4066-2
10. Humidity	at $T_A=85^{\circ}\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
11. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031